



iccad.com

New York, Metropolitan Area, USA
October/November, 2024

CALL FOR PAPERS

DEADLINES

April 28, 2024

Abstract Technical Submission

May 5, 2024

Paper Technical Submission

May 5, 2024

Proposal for Workshops, Tutorials,
Special Sessions, Panels

CONTACT

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Jointly sponsored by IEEE and ACM, ICCAD is the premier forum to explore new challenges, present leading-edge innovative solutions, and identify emerging technologies in the electronic design automation research areas. ICCAD covers the full range of CAD topics – from device and circuit level up through system level, as well as post-CMOS design. ICCAD has a long-standing tradition of producing cutting-edge, innovative technical program for attendees.

COVERED TOPICS

Original technical submissions on, but not limited to, the following topics are invited:

- System-Level CAD
- Synthesis, Verification, Physical Design, Analysis, Simulation, and Modeling
- CAD For Emerging Technologies, Paradigms

Paper submissions must be made through the online submission system at the ICCAD website. More details on the covered topics and the submission process will be provided soon.

CALL FOR PROPOSALS

In addition to presentations of technical submissions, ICCAD will also cover

- Workshops
- Tutorials
- Special Sessions
- Panels
- Keynotes

Corresponding proposals for the above will be greatly appreciated. A call for proposals will be distributed soon.

More information is available at www.iccad.com.